

Semicon Europa 2011: DuPont presents

Innovation and global collaboration in semiconductor processing

Learn how DuPont material innovation and global collaboration can help IC fabrication lines increase processing throughput and yields and benefit from global synergies.

- Meet the experts, discuss latest solutions for wafer production processes
- Interactive poster sessions running all through the day with lunch and snack buffet and drinks onsite
- Network with the global experts from DuPont:
 - Dr. Shuhong Wang, Kalrez® Senior Research Scientist, U.S.
 - Dave Lipnicke, Kalrez® & Vespel® Global Segment Manager Electronics, U.S.
 - Dr. Michele Vigliotti, Kalrez® & Vespel® Segment Manager Electronics, EMEA

Presentations & Poster Sessions at Semicon Europa, Dresden Wednesday, 12 October, 2011, 10:30 – 17:00 Meeting Room 1.8 in Hall 1

The program

- 10:30 – 11:30 Poster sessions and Q&A (details overleaf) - Join as you enter
- 11:30 – 12:15 Presentation – morning session:
- Industry trends influencing sealing material selection for plasma CVD and etch processes and how new Kalrez® products meet those requirements**
Presenter: Dr. Shuhong Wang, Kalrez® Senior Research Scientist, U.S.
- 12:15 – 13:30 Buffet lunch – Meeting with the specialists
- 13:30 – 14:15 Presentation – afternoon session :
- Industry trends influencing sealing material selection for plasma CVD and etch processes and how new Kalrez® products meet those requirements**
Presenter: Dr. Shuhong Wang, Kalrez® Senior Research Scientist, U.S.
- 14:30 – 17:00 Poster sessions and Q&A (details overleaf) – Join as you enter



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Interactive poster sessions

From 10:30 – 11:30 and from 14:30 – 17:00
Poster sessions and Q&A - Join as you enter

1. Industry trends influencing sealing material selection for plasma CVD and etch processes

Among the key factors, the increased thermal loads, the increased presence of oxidizers chemistry (i.e. ozone, steam, ammonia) and O₂ richest plasma chemistries influence on the requirements on sealing materials.

Presenter: Mrs Dr. Shuhong Wang, Kalrez® Senior Research Scientist, U.S.

2. Outgassing characterization of elastomeric seals used in semiconductor thermal wafer processing

Presenter: Dr. Michele Vigliotti, Kalrez® & Vespel® Regional Segment Manager Electronics, EMEA

3. DuPont IC fabrication technologies and products featured:

■ **DuPont™ Vespel® parts and shapes**

Presenter: Ritchie Greven, Kalrez® Sales Manager, Germany

■ **DuPont EKC Technology: removers, cleaners & strippers**

Presenter: Chris Reid, Senior Application Engineer, DuPont EKC Technology

■ **DuPont™ Teflon® fluoropolymers**

Presenter: Jeanne Driebeek, EMEA Product and Market Manager Teflon® FEP, PFA and Tefzel® ETFE

■ **DuPont™ Krytox® performance lubricants for semicon/vacuum pump applications**

Contact: Andreas Pölchen, Regional Business Manager EMEA, Krytox® Performance Lubricants

■ **DuPont™ Vertrel® fluorinated fluids for heat-transfer**

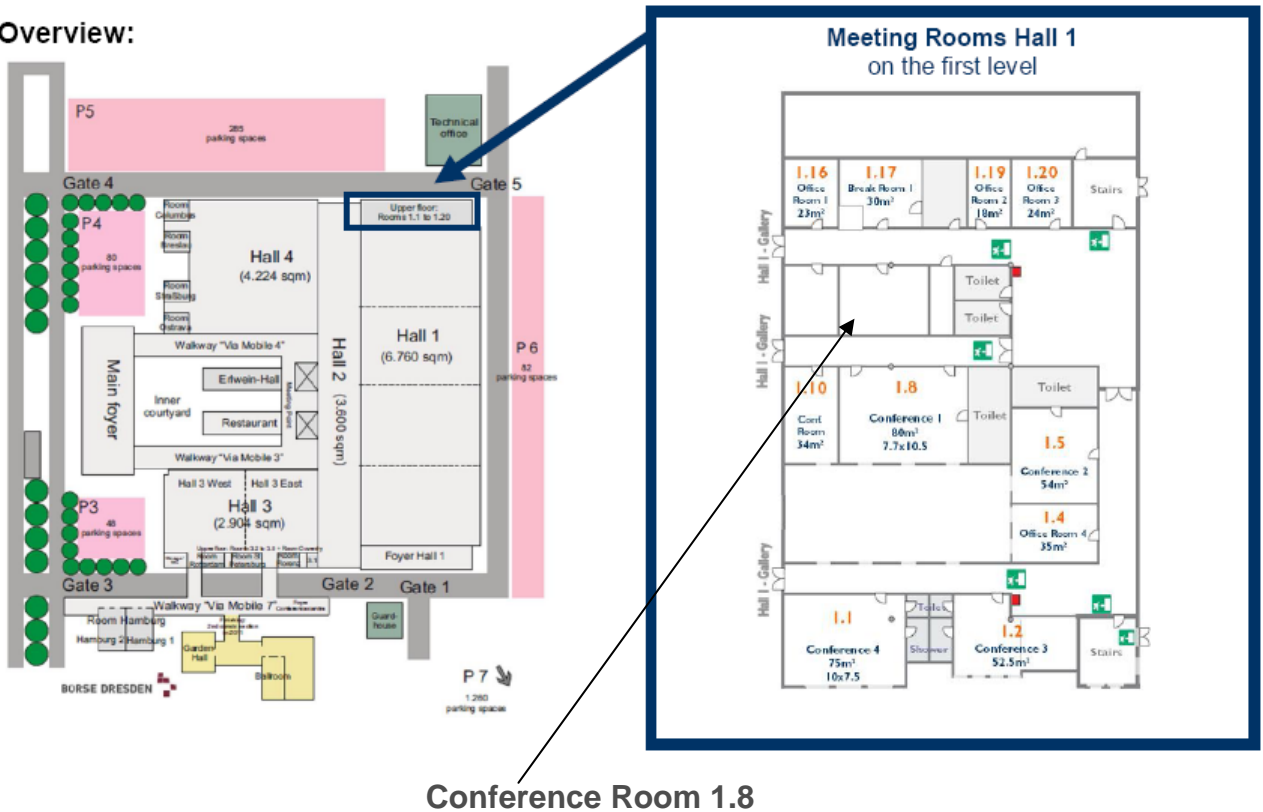
Contact: Luc Boulleau, DuPont de Nemours Int. Sàrl

Interested ? Register with us to receive your personal invitation!
Send an email to Noor.Alaradi@dupont.com

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Where to find us

Overview:



Conference Room 1.8

Presentations and Poster Sessions at Semicon Europa, Dresden
Wednesday, 12 October, 2011, 10:30 – 17:00
Meeting Room 1.8 in Hall 1

Free visitors tickets (until Oct 10) – order here:
<http://www.semiconeuropa.org/Register/Visitor>

